PATENT APPLICATION

Inventor:	Wen J. Meng
Serial No:	10/660,926
Filing Date:	September 12, 2003
Title:	Microscale Compression Molding of Metals with Surface Engineered Liga Inserts
Atty Docket:	Meng 0310

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

In accordance with the duty of candor and good faith imposed by 37 C.F.R. §1.56 and means of complying therewith according to 37 C.F.R. §§1.97 and 1.98, the references listed on the attached Information Disclosure Citation are called to the attention of the United States Patent and Trademark Office in connection with the above-identified patent application. Copies of the cited references are enclosed herewith. No admission is made that the cited art represents the prior art or that the cited art is the most material art.

The Office is urged to consider the cited references and to make an independent decision with respect to their materiality.

Respectfully submitted,

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January 27, 2004

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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CERTIFICATE OF FIRST CLASS MAILING

I hereby certify that the listed enclosures are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on January 27, 2004.

- Information Disclosure Statement
- Information Disclosure Citation
- Copies of six cited references
- Return postcard verifying receipt of the listed enclosures

André J. Porter
Registration No. 50,341

January 27, 2004

Substitute for form 1449A/PTO	U.S. Patent and Trademark Office U.S. Department of Commerce	COMPLETE IF KNOWN	
INFORMATION DISCLOSURE CITATION (use as many sheets as necessary)		**Application Number**	10/660,926
		Filing Date	September 12, 2003
		First Named Inventor	Wen J. Meng
		Art Unit	
		Examiner Name	
Sheet 1 of 1		Attorney Docket Number	Meng 0310

U.S. PATENT DOCUMENTS						
Exam. Initial	Document No.	Date	Name	Class	Subcl.	File Date

FOREIGN PATENT DOCUMENTS				
Exam. Initial	Foreign Patent Document Country Code / Number / Kind	Publication Date MM-DD-YY	Name of Patentee or Applicant of Cited Document	Translation ?

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)	
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	Cao *et al.*, "Microscale Compression Molding of Al with Surface Engineered LIGA Inserts," submitted for publication in June 2003
	Cao *et al.*, "Molding of Pb and Zn with Microscale Mold Inserts," presented at the Materials Research Society Meeting, Boston, Massachusetts (December 2002)
	Harris, C. *et al.*, "Design and Fabrication of a Cross Flow Micro Heat Exchanger," IEEE J. Microelectromech. Syst., Vol. 9, no. 4, pp. 502-508 (2000)
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EXAMINER SIGNATURE	DATE CONSIDERED

* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw a line through the citation if not in conformance and not considered. Include copy of this form with next communication to applicant.